Thermal Floor Panel MP741 & MP744



Technical Data Sheet

Thermal Floor Panel MP741 & MP744 is a composite insulation and chipboard flooring panel designed for use on concrete floor bases.

PRODUCT

Thermal Floor Panel MP741 & MP744 is suitable for new and refurbished buildings, conservatories and extensions using a variety of insulants.

Consisting of a moisture resistant chipboard factory-bonded to a thermal insulation layer to improve thermal performance through the floor structure.

SPECIFICATION

- · Easy to cut and install
- One operation saves time
- · Ready for floor covering
- Excellent thermal insulation

Extruded Polystyrene Thickness: 25mm, 35mm, 50mm Expanded Polystyrene Thickness: 20mm, 25mm, 50mm

PIR Thickness: 20mm, 25mm, 50mm Chipboard Thickness: 18mm or 22mm

Panel Size: 2400 x 600mm

Other insulant thicknesses are available

Thermal floor panel with T&G edges highlighted.

PRODUCT PERFORMANCE

	COMPRESSIVE STRENGTH	THERMAL CONDUCTIVITY
Extruded Polystyrene	200 kPa	0.033 W/mK
Expanded Polystyrene	70 kPa	0.038 W/mK
PIR	140 kPa	0.023 W/mK

Chipboard

C4 V313 Moisture Resistant Grade

Thermal Conductivity: 0.14 W/mK







IMPORTANT: Directions for use are given for guidance only and are not intended to form part of any contract. They should be varied or adapted to suit your particular materials or conditions of use. It is strongly recommended that prospective users test a sample of the product under their own conditions to satisfy themselves of its suitability for the intended purpose. For the Pre Completion Testing route to compliance with the Building Regulations Mayplas may provide site test evidence (where available) concerning the use of their product in a similar overall construction. Test evidence of a product passing minimum standards in one construction is not a warranty or specification that the same product will meet the desired acoustic performance level in any other building. Such evidence can only be considered indicative and should not be relied upon.